



Features

Environments

And Robust End Application

Low Input Capacitance Fast Switching Speed

Low R_{DS(ON)} - Minimizes On-State Losses

40V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Rated to +175°C - Ideal for High Ambient Temperature

Lead-Free Finish; RoHS Compliant (Notes 1 & 2)

Halogen and Antimony Free. "Green" Device (Note 3)

Qualified to AEC-Q101 Standards for High Reliability

An Automotive-Compliant Part is Available Under Separate

100% Unclamped Inductive Switching - Ensures More Reliable

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D T _C = +25°C (Note 9)
40V	$3.3 \text{m}\Omega @ V_{GS} = 10V$	100A
	$5.0 \text{m}\Omega @ V_{GS} = 5V$	95A

Description

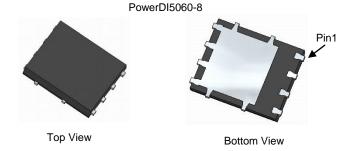
This new generation N-Channel Enhancement Mode MOSFET is designed to minimize $R_{\text{DS(ON)}}$, yet maintain superior switching performance.

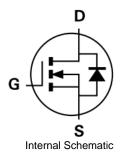
Applications

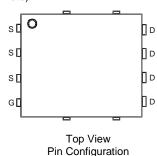
- BLDC Motors
- DC-DC Converters
- Loadswitch

Datasheet (DMTH43M8LPSQ)

- Case: PowerDI 5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (2)
- Weight: 0.097 grams (Approximate)





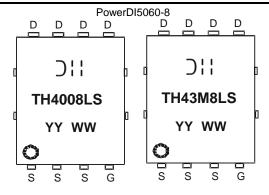


Ordering Information (Note 4)

Part Number	Case	Packaging
DMTH43M8LPS-13	PowerDI5060-8	2,500/Tape & Reel

- Notes: 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 - 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 - 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information





Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	40	V	
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current, V _{GS} = 10V (Note 5)	$T_A = +25^{\circ}C$ $T_A = +100^{\circ}C$	I _D	22 15.5	А
Continuous Drain Current, V _{GS} = 10V (Note 6) (Note 9)	$T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$	I_D	100 82	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	350	А	
Maximum Continuous Body Diode Forward Current (Note 6)	Is	69	А	
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)		I _{SM}	350	Α
Avalanche Current, L = 1mH		I _{AS}	13.2	Α
Avalanche Energy, L = 1mH		E _{AS}	87	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25$ °C	P_{D}	2.7	W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\theta JA}$	55	°C/W
Total Power Dissipation (Note 6)	T _C = +25°C	P _D	83	W
Thermal Resistance, Junction to Case (Note 6)		R _{eJC}	1.8	°C/W
Operating and Storage Temperature Range		$T_{J_{i}}T_{STG}$	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

		1	1	1	1		
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	40	_	_	V	$V_{GS} = 0V$, $I_D = 1mA$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 32V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	1	_	2.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance		_	2.7	3.3	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Diain-Source On-Resistance	R _{DS(ON)}	_	3.6	5.0	11122	$V_{GS} = 5V, I_D = 15A$	
Diode Forward Voltage	V _{SD}	_	_	1.2	V	V _{GS} = 0V, I _S = 20A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{ISS}	_	2,693	_		$V_{DS} = 30V$, $V_{GS} = 0V$, $f = 1MHz$	
Output Capacitance	Coss	_	1,172	_	pF		
Reverse Transfer Capacitance	C _{RSS}	_	52	_			
Gate Resistance	R _G	_	2.54	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 10V)	Q_G	_	38.5	_		V _{DS} = 30V, I _D = 20A	
Total Gate Charge (V _{GS} = 4.5V)	Q_G	_	17.6	_	nC		
Gate-Source Charge	Q _{GS}	_	6.9	_	IIC		
Gate-Drain Charge	Q_{GD}	_	6.9	_			
Turn-On Delay Time	t _{D(ON)}	_	5.2	_		$V_{DD} = 30V, V_{GS} = 10V,$ $I_{D} = 20A, R_{G} = 3\Omega$	
Turn-On Rise Time	t _R	_	5.7	_			
Turn-Off Delay Time	t _{D(OFF)}	_	23.5	_	ns		
Turn-Off Fall Time	t _F	_	11	_			
Body Diode Reverse Recovery Time	t _{RR}	_	35.4	_	ns	1 000 11/14 1000/	
Body Diode Reverse Recovery Charge	Q _{RR}	_	32.9	_	nC	I _F = 20A, di/dt = 100A/μs	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.

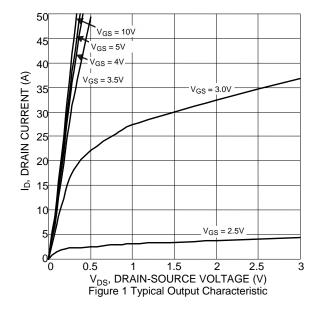
6. Thermal resistance from junction to soldering point (on the exposed drain pad).

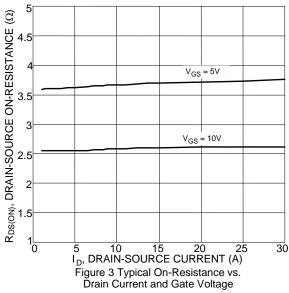
7. Short duration pulse test used to minimize self-heating effect.

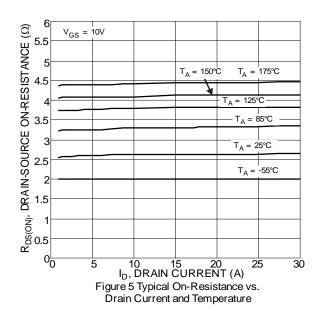
8. Guaranteed by design. Not subject to product testing.

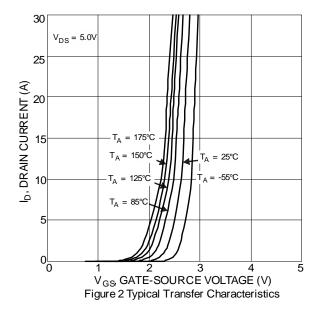
9. Package limit.

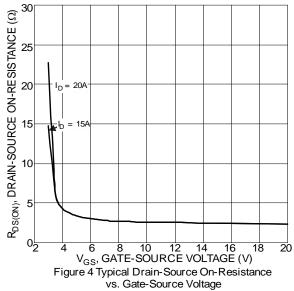


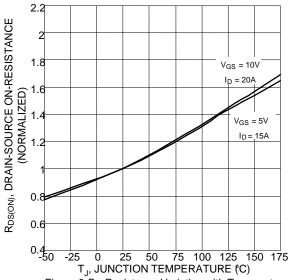
















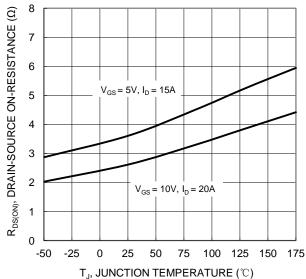
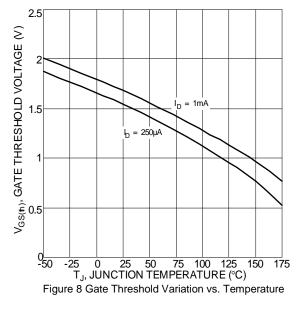
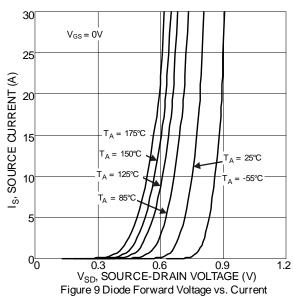


Figure 7. On-Resistance Variation with Temperature





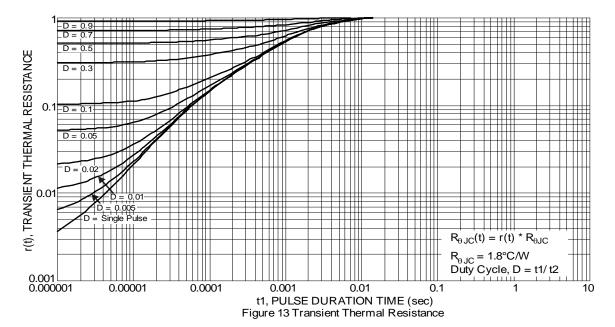
10 9 8 7 6 $V_{GS}(V)$ 5 4 $V_{DS} = 20V, I_{D} = 20A$ 3 2 0 0 5 10 15 20 25 30 35 40 Qg (nC) Figure 11. Gate Charge

10000 f = 1MHzC_T, JUNCTION CAPACITANCE (pF) C_{iss} 1000 100 $\mathsf{C}_{\mathsf{rss}}$ 10 0 5 10 15 20 25 30 35 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 10. Typical Junction Capacitance

1000 $R_{DS(ON)}$ LIMITED 100 ID, DRAIN CURRENT (A) P_w=10µs 10 $T_{J(MAX)}$ =175°C _w=10ms P_w=100ms Single Pulse DUT on infinite heatsink V_{GS}=10V 0.1 0.1 100 1 10

V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



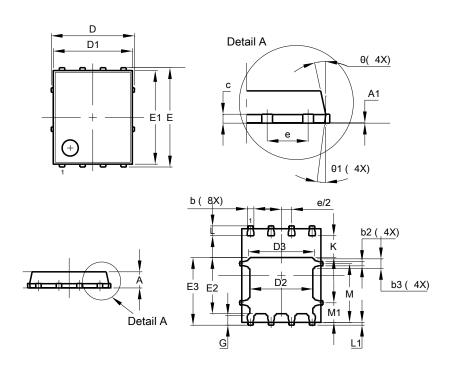




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8

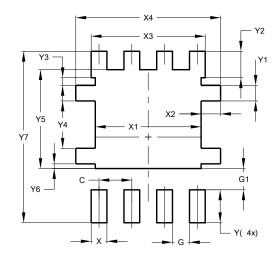


PowerDI5060-8				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A1	0.00	0.05	_	
b	0.33	0.51	0.41	
b2	0.200	0.350	0.273	
b3	0.40	0.80	0.60	
С	0.230	0.330	0.277	
D		5.15 BSC		
D1	4.70	5.10	4.90	
D2	3.70	4.10	3.90	
D3	3.90	4.30	4.10	
Е	(3.15 BSC	;	
E1	5.60	6.00	5.80	
E2	3.28	3.68	3.48	
E3	3.99	4.39	4.19	
е	,	1.27 BSC	;	
G	0.51	0.71	0.61	
K	0.51	_	_	
L	0.51	0.71	0.61	
L1	0.100	0.200	0.175	
М	3.235	4.035	3.635	
M1	1.00	1.40	1.21	
θ	10°	12°	11°	
θ1	6°	8°	7°	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8



Dimensions	Value (in mm)			
С	1.270			
G	0.660			
G1	0.820			
X	0.610			
X1	4.100			
X2	0.755			
Х3	4.420			
X4	5.610			
Υ	1.270			
Y1	0.600			
Y2	1.020			
Y3	0.295			
Y4	1.825			
Y5	3.810			
Y6	0.180			
Y7	6.610			



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